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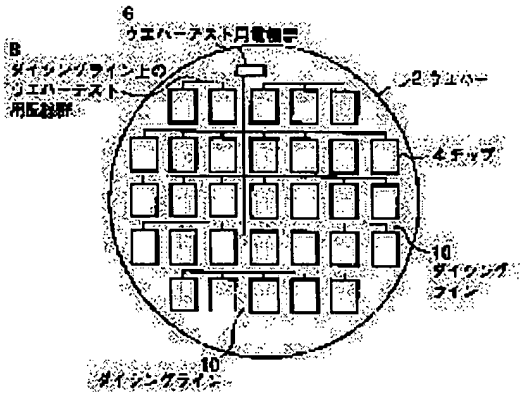
(54) SEMICONDUCTOR DEVICE AND METHOD OF TESTING WAFER

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a semiconductor device capable of executing the wafer test at a high speed.

SOLUTION: Chips 4 on a wafer 2 are wired by utilizing wirings formed on a dicing line 10. The wiring is made every unit of specified no. of chips arranged e.g. like a matrix. For testing the wafer, the wired chips are tested in parallel or with electrically scanning the wired chips.



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